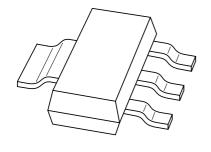
DISCRETE SEMICONDUCTORS

DATA SHEET



PBSS5540Z 40 V low V_{CEsat} PNP transistor

Product specification Supersedes data of 2001 Jan 26 2001 Sep 21





40 V low V_{CEsat} PNP transistor

PBSS5540Z

FEATURES

- Low collector-emitter saturation voltage
- · High current capability
- Improved device reliability due to reduced heat generation.

APPLICATIONS

- Supply line switching circuits
- · Battery management applications
- DC/DC converter applications
- · Strobe flash units
- Heavy duty battery powered equipment (motor and lamp drivers)
- MOSFET driver applications.

DESCRIPTION

PNP low V_{CEsat} transistor in a SOT223 plastic package. NPN complement: PBSS4540Z.

MARKING

TYPE NUMBER	MARKING CODE
PBSS5540Z	PB5540

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX	UNIT
V _{CEO}	emitter-collector voltage	-40	V
I _C	collector current (DC)	- 5	Α
I _{CM}	peak collector current	-10	Α
R _{CEsat}	equivalent on-resistance	<80	mΩ

PINNING

PIN	DESCRIPTION
1	base
2	collector
3	emitter
4	collector

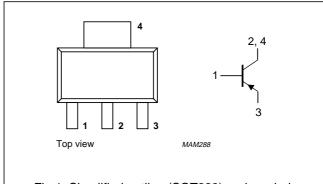


Fig.1 Simplified outline (SOT223) and symbol.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-40	V
V _{CEO}	collector-emitter voltage	open base	_	-40	V
V _{EBO}	emitter-base voltage	open collector	_	-6	V
I _C	collector current (DC)		_	- 5	Α
I _{CM}	peak collector current		_	-10	А
I _{BM}	peak base current		_	-2	Α
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	1.35	W
		T _{amb} ≤ 25 °C; note 2	_	2	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Notes

- 1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².
- 2. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 6 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient	in free air; note 1	92	K/W

Note

1. Device mounted on a printed-circuit board, single-sided copper, tinplated, mounting pad for collector 1 cm².

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CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

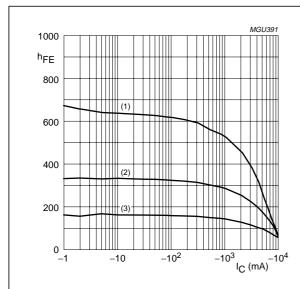
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = -30 \text{ V}; I_E = 0$	_	_	-100	nA
		$V_{CB} = -30 \text{ V}; I_E = 0; T_j = 150 ^{\circ}\text{C}$	_	_	-50	μΑ
I _{EBO}	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; I_C = 0$	_	_	-100	nA
h _{FE}	DC current gain	$V_{CE} = -2 \text{ V}; I_{C} = -500 \text{ mA}$	250	350	_	
		$V_{CE} = -2 \text{ V}; I_{C} = -1 \text{ A}; \text{ note 1}$	200	300	_	
		$V_{CE} = -2 \text{ V}; I_{C} = -2 \text{ A}; \text{ note 1}$	150	250	_	
		$V_{CE} = -2 \text{ V}; I_{C} = -5 \text{ A}; \text{ note 1}$	50	150	_	
V _{CEsat}	collector-emitter saturation voltage	$I_C = -500 \text{ mA}; I_B = -5 \text{ mA}$	_	-80	-120	mV
		$I_C = -1 \text{ A}; I_B = -10 \text{ mA}$	_	-120	-170	mV
		$I_C = -2 \text{ A}; I_B = -200 \text{ mA}$	_	-110	-160	mV
R _{CEsat}	equivalent on-resistance	$I_C = -2 \text{ A}$; $I_B = -200 \text{ mA}$; note 1	_	<55	<80	mΩ
V_{CEsat}	collector-emitter saturation voltage	$I_C = -5 \text{ A}; I_B = -500 \text{ mA}$	_	-250	-375	mV
V_{BEsat}	base-emitter saturation voltage	$I_C = -5 \text{ A}; I_B = -500 \text{ mA}$	_	_	-1.3	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; I_{C} = -2 \text{ A}$	_	-0.8	-1.25	V
f _T	transition frequency	I _C = -100 mA; V _{CE} = -10 V; f = 100 MHz	60	120	_	MHz
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; I_E = I_e = 0;$ f = 1 MHz	_	90	105	pF

Note

1. Pulse test: $t_p \le 300~\mu s;~\delta \le 0.02.$

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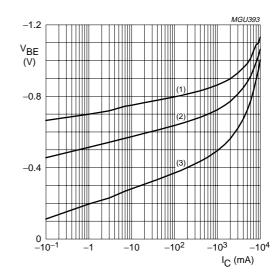
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 $V_{CE} = -2 V$.

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) T_{amb} = 25 °C.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

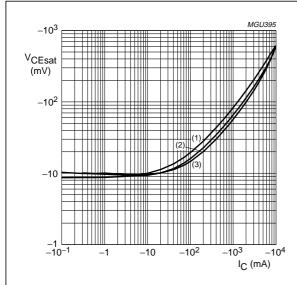
Fig.2 DC current gain as a function of collector current; typical values.



 $V_{CE} = -2 V$.

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

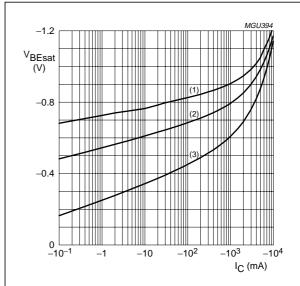
Fig.3 Base-emitter voltage as a function of collector current; typical values.



 $I_{\rm C}/I_{\rm B} = 20.$

- (1) $T_{amb} = 150 \, ^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.4 Collector-emitter saturation voltage as a function of collector current; typical values.



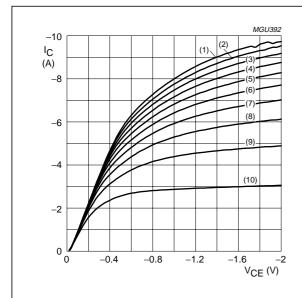
 $I_{\rm C}/I_{\rm B}=20$.

- (1) $T_{amb} = 150 \,^{\circ}C$.
- (2) $T_{amb} = 25 \, ^{\circ}C$.
- (3) $T_{amb} = -55 \,^{\circ}C$.

Fig.5 Base-emitter saturation voltage as a function of collector current; typical values.

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 $T_{amb} = 25 \, ^{\circ}C.$

(1) $I_B = -150 \text{ mA}$.

(5) $I_B = -90 \text{ mA}.$

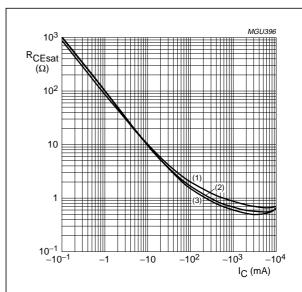
(9) $I_B = -30 \text{ mA}.$ (10) $I_B = -15 \text{ mA}.$

(2) $I_B = -135 \text{ mA}.$ (3) $I_B = -120 \text{ mA}.$ (6) $I_B = -75 \text{ mA}.$ (7) $I_B = -60 \text{ mA}.$

(4) $I_B = -105 \text{ mA}$.

(8) $I_B = -45 \text{ mA}.$

Fig.6 Collector current as a function of collector-emitter voltage; typical values.



 $I_{\rm C}/I_{\rm B} = 20$.

(1) $T_{amb} = 150 \,^{\circ}C$.

(2) $T_{amb} = 25 \, ^{\circ}C$.

(3) $T_{amb} = -55 \, ^{\circ}C$.

Fig.7 Collector-emitter equivalent on-resistance as a function of collector current; typical values.

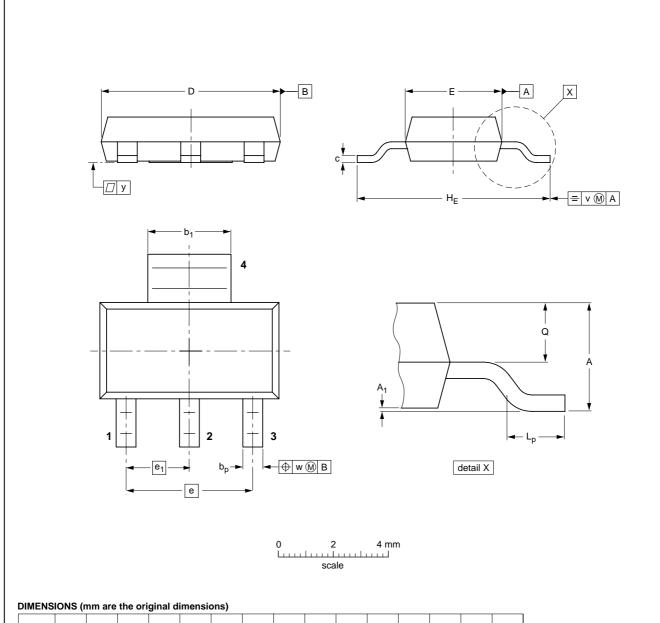
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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



UNIT	A	A ₁	bp	b ₁	С	D	E	е	e ₁	HE	Lp	Q	٧	w	у
mm	1.8 1.5	0.10 0.01	0.80 0.60	3.1 2.9	0.32 0.22	6.7 6.3	3.7 3.3	4.6	2.3	7.3 6.7	1.1 0.7	0.95 0.85	0.2	0.1	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT223			SC-73			-97-02-28 99-09-13

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DATA SHEET STATUS

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NOTES

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Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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Printed in The Netherlands

613514/04/pp12

Date of release: 2001 Sep 21

Document order number: 9397 750 08434

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